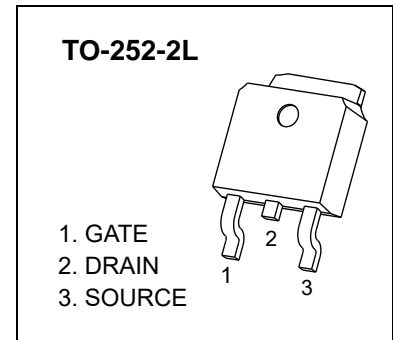




TO-252-2L Plastic-Encapsulate MOSFETS

CJU02N60M1 N-Channel Power MOSFET

| | | |
|---------------|-----------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(on)MAX}$ | I_D |
| 600V | 2.7Ω@10V | 2A |



General Description

The high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power suppliers, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

FEATURES

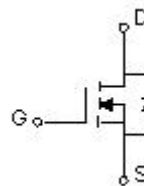
- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperature

MARKING



U02N60M1= Device code
 Solid dot = Green molding compound device,
 if none, the normal device
 XXXX=Code

EQUIVALENT CIRCUIT



Maximum ratings ($T_a=25^{\circ}C$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|-----------------------|-----------|------|
| Drain-Source Voltage | V_{DS} | 600 | V |
| Gate-Source Voltage | V_{GS} | ±30 | |
| Continuous Drain Current | $I_D^{(1)}$ | 2 | A |
| Pulsed Drain Current | $I_{DM}^{(2)}$ | 8 | |
| Single Pulsed Avalanche Energy | $E_{AS}^{(3)}$ | 88 | mJ |
| Power Dissipation | $P_D^{(1)}$ | 31 | W |
| Thermal Resistance from Junction to Ambient | $R_{\theta JA}^{(6)}$ | 100 | °C/W |
| Thermal Resistance from Junction to Case | $R_{\theta JC}^{(1)}$ | 4 | °C/W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 ~+150 | °C |

MOSFET ELECTRICAL CHARACTERISTICS

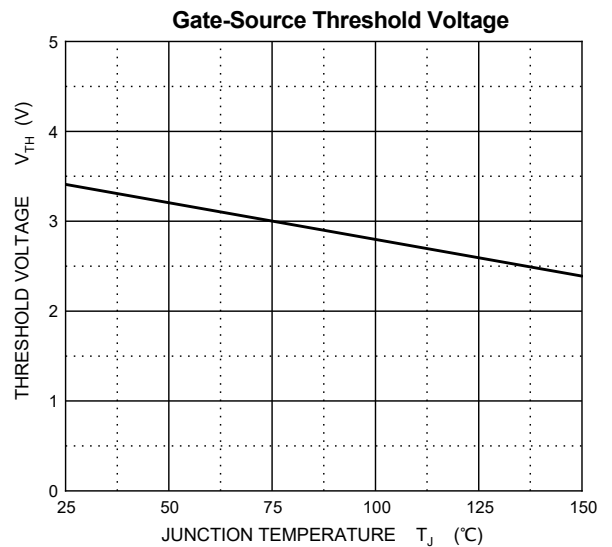
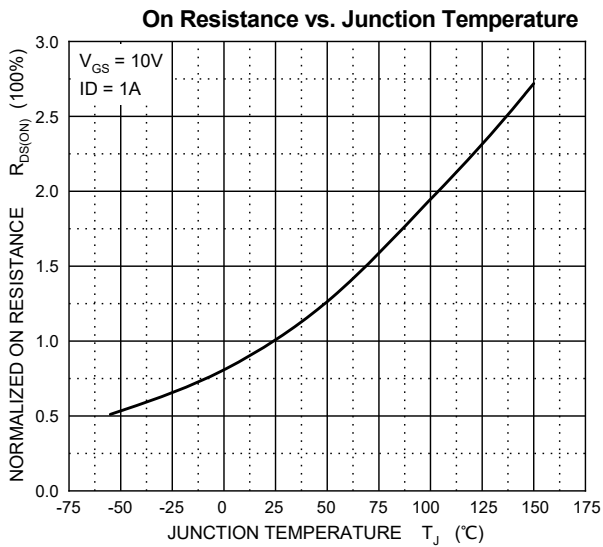
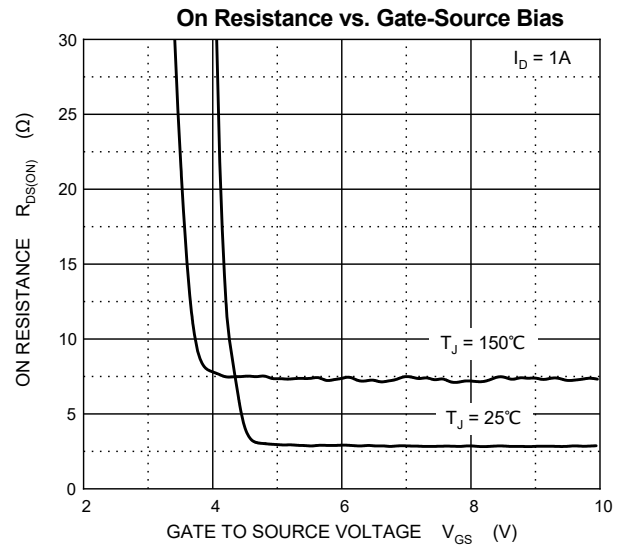
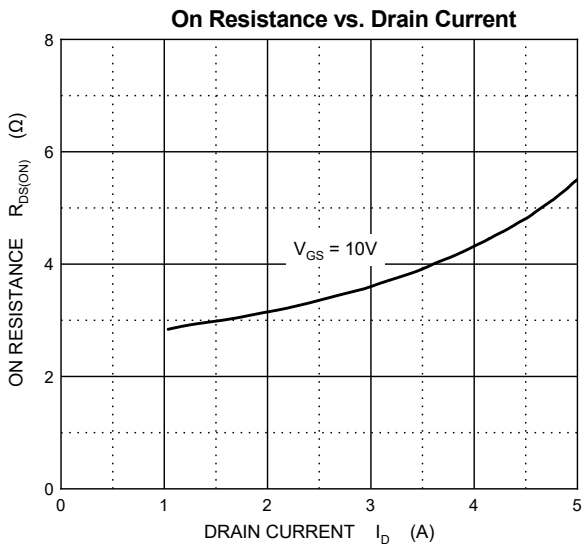
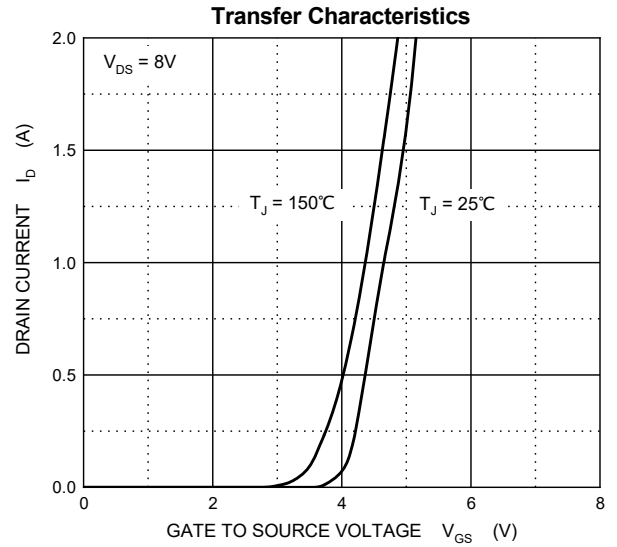
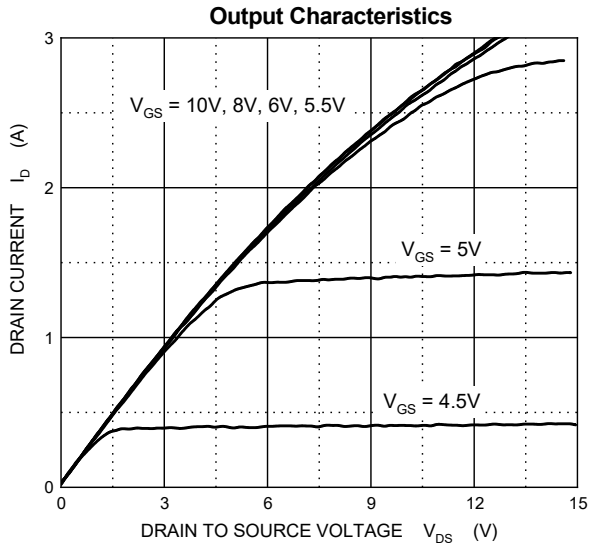
$T_J = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|---|-----------------------|--|-----|------|-----------|----------|
| Off characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 600 | | | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=600V, V_{GS}=0V$ | | | 1.0 | μA |
| Gate-body leakage current | I_{GSS} | $V_{DS}=0V, V_{GS}=\pm 30V$ | | | ± 100 | nA |
| On characteristics ^④ | | | | | | |
| Gate-threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | 3.4 | 4.0 | V |
| Static drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=1A$ | | 2.7 | 3.7 | Ω |
| Dynamic characteristics ^⑤ | | | | | | |
| Input capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V,$ $f=1MHz$ | | 322 | | pF |
| Output capacitance | C_{oss} | | | 38 | | |
| Reverse transfer capacitance | C_{rss} | | | 7 | | |
| Gate resistance | R_g | $f=1MHz$ | | 5.7 | | Ω |
| Switching characteristics ^⑤ | | | | | | |
| Total gate charge | Q_g | $V_{GS}=10V,$ $V_{DS}=25V, I_D=2A$ | | 1.6 | | nC |
| Gate-source charge | Q_{gs} | | | 2.1 | | |
| Gate-drain charge | Q_{gd} | | | 6.2 | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=25V, V_{GS}=10V,$ $R_G=18\Omega, I_D=2A$ | | 1.8 | | nS |
| Turn-on rise time | t_r | | | 3.2 | | |
| Turn-off delay time | $t_{d(off)}$ | | | 7.4 | | |
| Turn-off fall time | t_f | | | 7.6 | | |
| Drain-Source Diode Characteristics | | | | | | |
| Drain-source diode forward voltage | V_{SD} ^④ | $V_{GS}=0V, I_S=2A$ | | | 1.4 | V |
| Continuous drain-source diode forward current | I_S ^① | | | | 2.0 | A |
| Pulsed drain-source diode forward current | I_{SM} ^② | | | | 8.0 | A |
| Reverse recovery time | t_{rr} | $dI_F/dt = 100A/\mu s,$ $I_S = 2A, V_{DD} = 400V$ | | 192 | | ns |
| Reverse recovery charge | Q_{rr} | | | 1027 | | nC |

Notes:

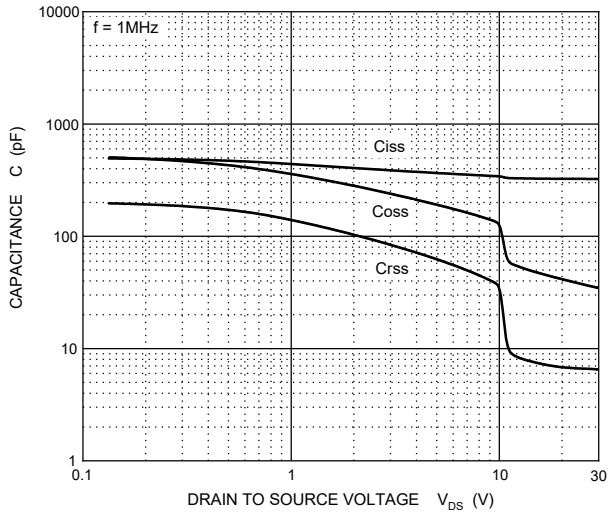
- $T_C=25^\circ\text{C}$ Limited only by maximum temperature allowed.
- $P_W \leq 10\mu s$, Duty cycle $\leq 1\%$.
- EAS condition: $V_{DD}=150V, V_{GS}=10V, L=10mH, R_g=25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production.
- The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^\circ\text{C}$.

Typical Characteristics

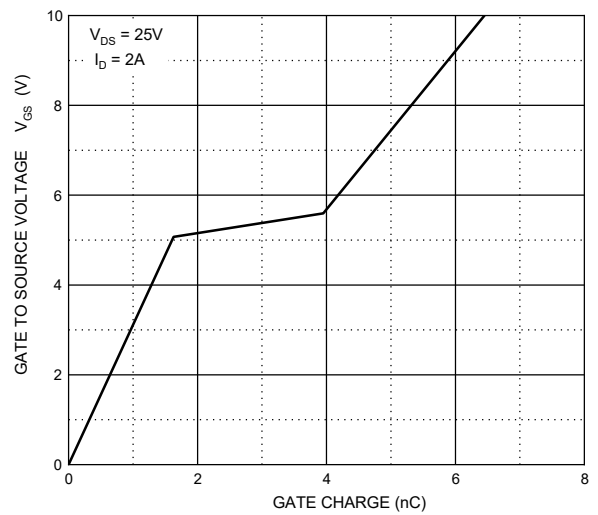


Typical Characteristics

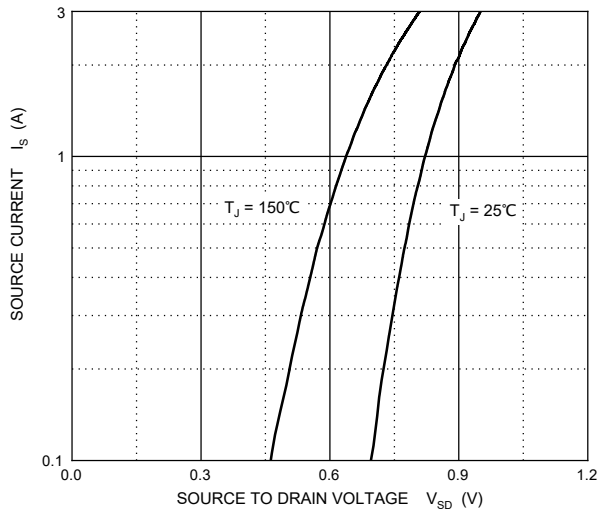
Typical Capacitances



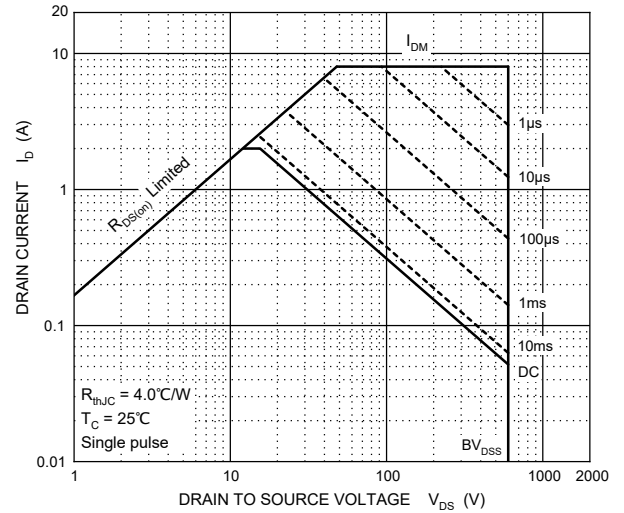
Gate Charge



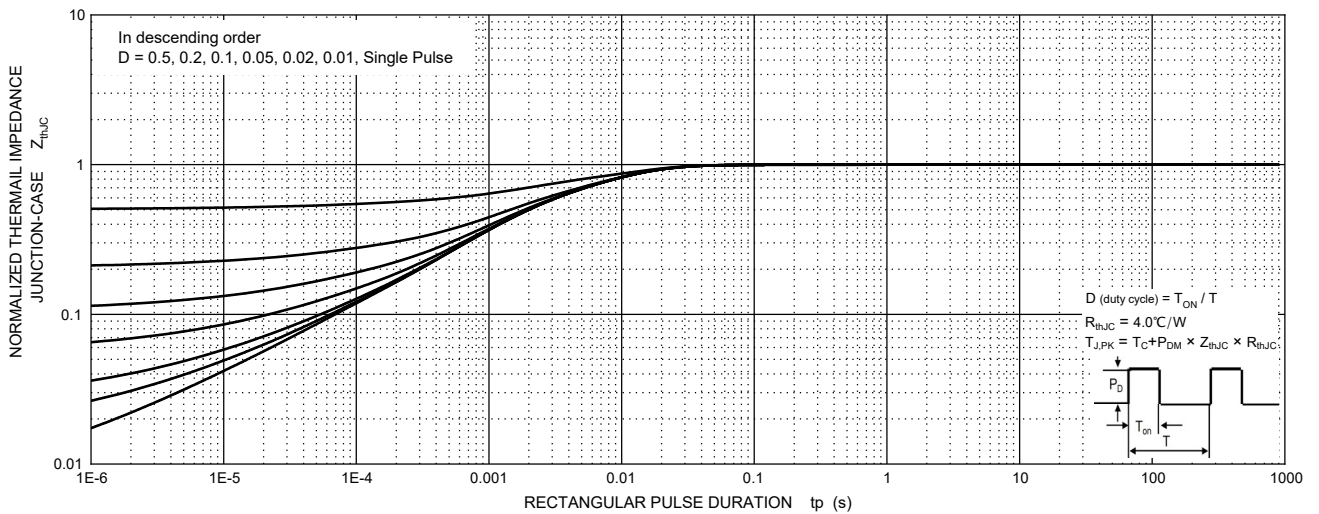
Source-Drain Diode Forward Characteristics



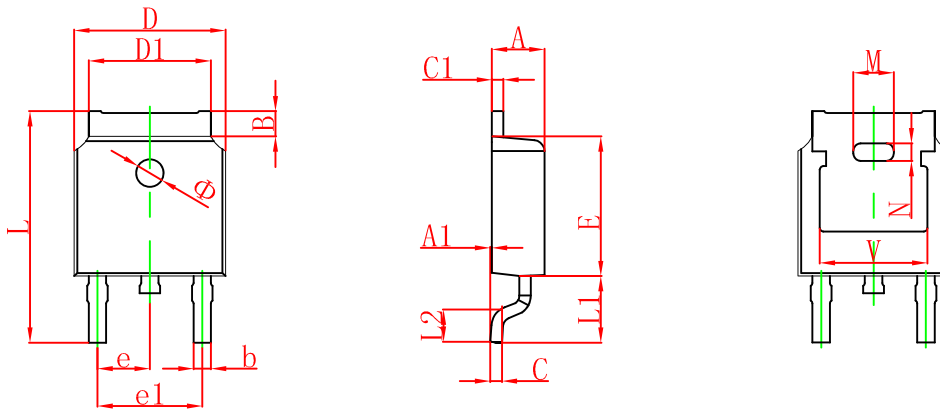
Maximum Safe Operating Area



Transient Thermal Impedance, Junction-Case

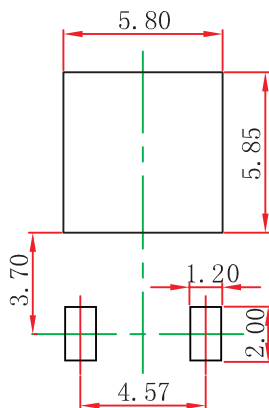


TO-252(4R)-2L Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.380 | 0.087 | 0.094 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| B | 0.800 | 1.400 | 0.031 | 0.055 |
| b | 0.710 | 0.810 | 0.028 | 0.032 |
| c | 0.460 | 0.560 | 0.018 | 0.022 |
| c1 | 0.460 | 0.560 | 0.018 | 0.022 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.130 | 5.460 | 0.202 | 0.215 |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.286 TYP. | | 0.090 TYP. | |
| e1 | 4.327 | 4.727 | 0.170 | 0.186 |
| M | 1.778REF. | | 0.070REF. | |
| N | 0.762REF. | | 0.018REF. | |
| L | 9.800 | 10.400 | 0.386 | 0.409 |
| L1 | 2.9REF. | | 0.114REF. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| V | 4.830 REF. | | 0.190 REF. | |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 |

TO-252(4R)-2L Suggested Pad Layout



Note:

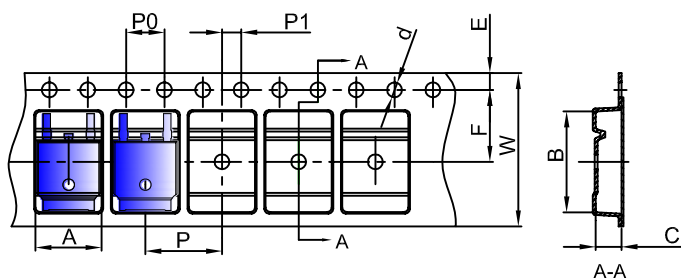
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

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To-252(4R)-2L Tape and Reel

TO-252 Embossed Carrier Tape

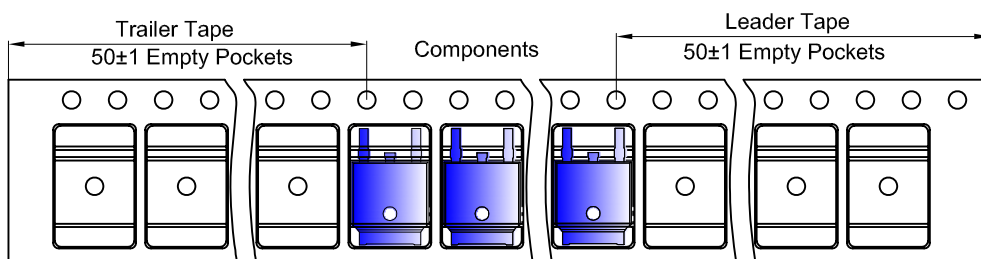


Packaging Description:

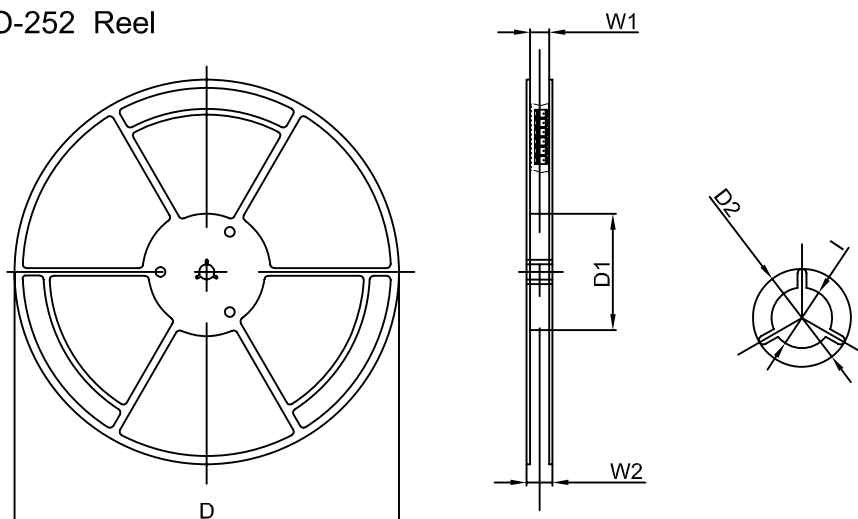
TO-252 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 25,00 units per 13" or 33.0 cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

| Dimensions are in millimeter | | | | | | | | | | |
|------------------------------|--------|--------|--------|--------|--------|--------|--------|--------|--------|-----------|
| Pkg type | A | B | C | d | E | F | P0 | P | P1 | W |
| TO-252 | 6.90 | 10.50 | 2.70 | Ø1.55 | 1.75 | 7.50 | 4.00 | 8.00 | 2.00 | 16.00 |
| (Tolerance) | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +/-0.1 | +0.3/-0.1 |

TO-252 Tape Leader and Trailer



TO-252 Reel



| Dimensions are in millimeter | | | | | | |
|------------------------------|--------|--------|--------|-------|-------|--------|
| Reel Option | D | D1 | D2 | W1 | W2 | I |
| 13"Dia | 330.00 | 100.00 | Ø21.00 | 16.40 | 21.00 | Ø13.00 |
| Tolerance | +/-2 | +/-1 | +/-1 | +/-1 | +/-1 | +/-1 |

| REEL | Reel Size | Box | Box Size(mm) | Carton | Carton Size(mm) | G.W.(kg) |
|-----------|-----------|-----------|--------------|------------|-----------------|----------|
| 2,500 pcs | 13inch | 2,500 pcs | 340×336×29 | 25,000 pcs | 353×346×365 | 14.04 |

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